

IEEE/SICE SII 2024

International Symposium on System Integration HA LONG, VIETNAM 8-11th January, 2024









Ha Long Bay

IEEE/SICE International Symposium on System Integration (SII) is the symposium series presenting the state of the art and future perspectives of system integration, where industrial experts, researchers, and academics share ideas and experiences surrounding frontier technologies, breakthrough and innovative solutions, and applications.

The IEEE/SICE SII 2024 will be the 16th symposium on system integration. System integration is one of the key technologies and the integration of hardware and software is especially important to solve the industrial or social system problems in the new century. This symposium focuses towards new research and industrial applications of system integration, and discusses approaches and methodologies to improve effectiveness of system integration.

Important Dates:

Proposals for Special Sessions Jun. 30, 2023 Paper Submission Aug. 1, 2023 Aug.15, 2023 Workshop Proposal Submission Deadline Notification of Workshop Proposal Acceptance Sep.15, 2023 Notification of Paper Acceptance Oct. 1, 2023 Final Paper Submission Oct. 15, 2023 Oct. 15, 2023 Late Breaking Results Submission

Notification of Late Breaking Results Acceptance

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Oct. 29, 2023



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